

Detector Performances on Warm/Cold Machine

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with

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Introduction

- Some of the ITRP members want information on the detector issues at Warm/Cold Machine
- Someone says “The information might not be so important for the technology choice”, but he can say so because he knows that.
- It is our duty to give them the information, if they require it. Wise persons have sense of responsibility, and will not make decision without knowledge.
- We discussed on the cases of Vertex Detector, Central Tracker, and Calorimeter. Our conclusions was privately sent to a ITRP member in response to his request. It was also sent to SLAC via Toge-san.

Vertex Detector

- Design Criteria:

$$\sigma_b = 5 \text{ \AA} \cdot 10 / (p\beta \sin^{3/2}\theta) \text{ \mu m}$$

- Requirement for the detector

- $\sigma_x < 3\text{ \mu m}$
- $t < 0.1\% X_0$ (Si:100 \mu m)
- Radiation tolerance for $R=10\sim 15\text{ mm}$
- Readout Speed: 6.7ms for GLC / 50 \mu s for TESLA

- Possible Technology for Cold Machine:

- Column Parallel Readout
- Digital CMOS
- Analog buffered CMOS

Vertex Detector (Cont.)

- Other Problem in Cold Machine
 - RF pickup noise
 - Happened at SLD
 - 100ns(?) loss to wait for the damp for every 330ns bunch interval
 - Signal diffusion in the epitaxial layer of CCD/CMOS
 - Key of excellent spatial resolution
 - Takes ~100ns
- Still more high speed readout necessary

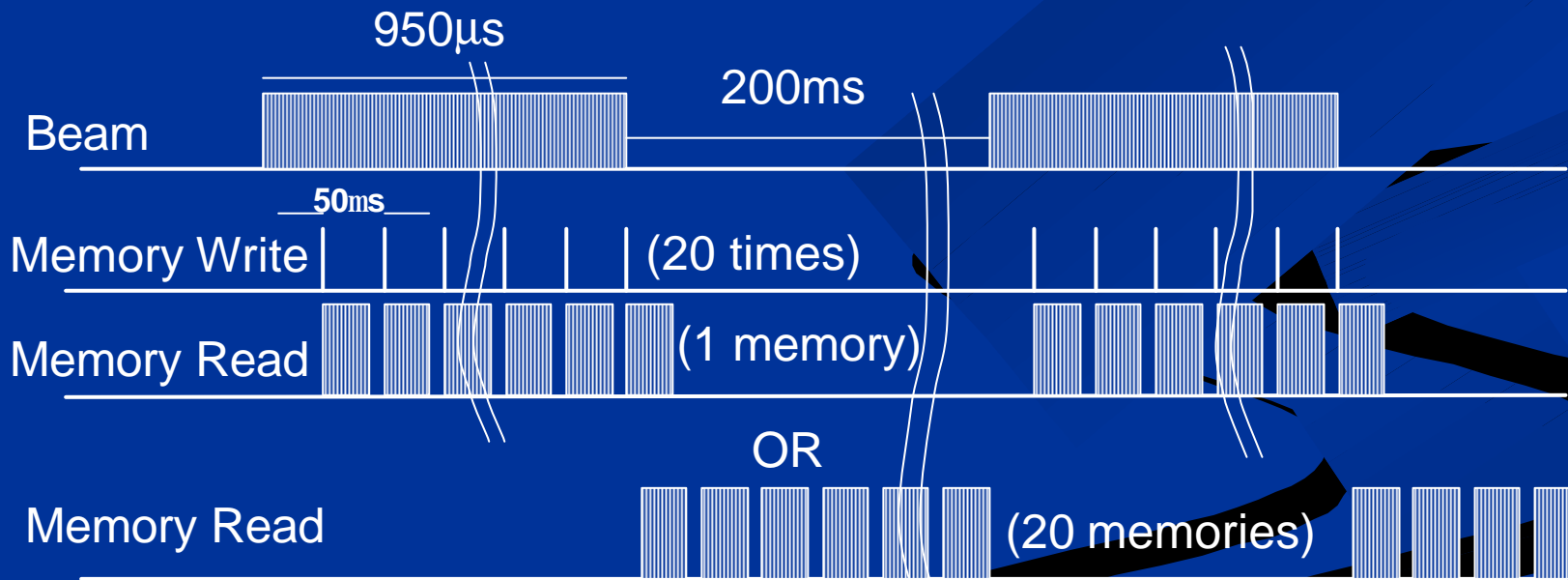
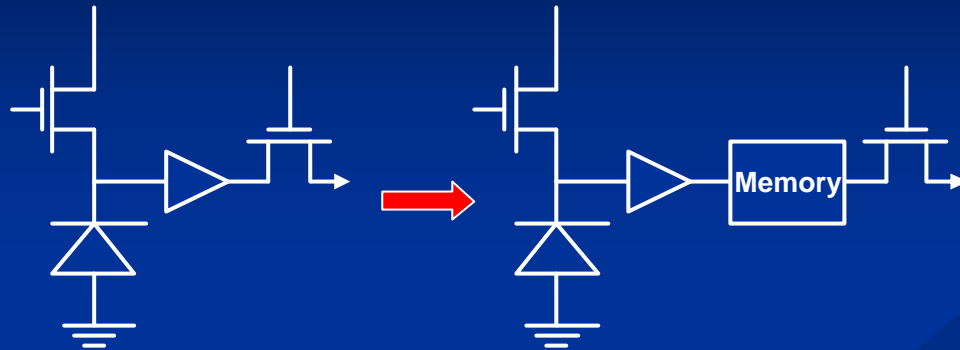
Vertex Detector (Cont.)

■ Score:

- 5: Demonstrated, 4: Will be demonstrated in 2~3 years, 3: Need large R&D effort, 2: Quite difficult, 1: Almost hopeless

	σ_x ($<3\mu\text{m}$)	Thickness ($<100\mu\text{m}$)	Speed (Warm) (6ms)	Speed (Cold) (50 μs)
CCD	5	4	4	1
CP-CCD	5	4	4	3
CP-CMOS	5	4	4	3
Digital CMOS	5	4	4	3
Analog-buffered CMOS	4	4	4	3
Hybrid Active Pixel	3	2	5	5

Analog-buffered CMOS



Central Tracker

	Time stamping capability	Bunch ID		Space charge effect	
		Warm	Cold	Warm	Cold
TPC	2~3 ns ⁽¹⁾	(1) / (2)		(4)	(4)
CDC	2 ns	/ (3)			×

- (1) With z-measurement external detector
- (2) With z- and t-measurement external detector
- (3) With t-measurement external detector
- (4) Need gating grid

Central Tracker (Cont.)

- External z-measurement (Si IT) is mandatory for TPC at Warm machine
- Effect of t-measurement device (Sci-Fi with Si-PM) needs simulation study

Calorimeter

- Bunch ID in every fine-segmented cell is preferable ---
Machine/Det-option dependent
 - Cold Machine: No problem
 - Warm Machine:
 - W-Si: Poor bunch ID capability. Combination with high speed device
 - Pb-Sci: Analog signal → ADC and TAC/ADC
Two successive hits in 100ns on the same cell
cannot be separated
- Separation of event overlap is not studied well
→ Simulation effort is necessary

Conclusion

(Not sent to the ITRP member)

	Warm	Cold
Vertex Detector	10	7
Central Tracker	9	10
Calorimeter	9	10
Others	?	?
Total	?	?

More study (Simulation + Det. R&D) is necessary